

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Harald Bottner et al.

Application No.: 10/789,423

Confirmation No.: 5684

Filed: February 27, 2004

Art Unit: 2826

For: SOLDER, MICROELECTROMECHANICAL  
COMPONENT AND DEVICE, AND A  
PROCESS FOR PRODUCING A  
COMPONENT OR DEVICE

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Examiner: B. P. Sandvik

**SUBMISSION WITH REQUEST FOR CONTINUED EXAMINATION (RCE)**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated September 11, 2006, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.